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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kinsman et al.

Serial No.: 09/917,127

Filed: June 27, 2001

For: METHOD FOR FABRICATING A CHIP
SCALE PACKAGE USING WAFER LEVEL
PROCESSING AND DEVICES RESULTING
THEREFROM

Examiner: Unknown

Group Art Unit: 2815

Attorney Docket No.: 3572.1US (97-1243.1)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

October 26, 2001
Date of Deposit

Signature of registered practitioner or other person
having reasonable basis to expect mailing to occur
on date of deposit shown pursuant to 37 C.F.R. §
1.8(a)(1)(ii)

Joseph A. Walkowski
Typed/printed name of person whose signature is
contained above

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO-1449 be considered by the Examiner and made of record. The listed documents are from co-pending application Serial No. 09/586,243, filed June 2, 2000. Copies of the listed documents are enclosed pursuant to 37 C.F.R. § 1.98(a).

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as

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defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicants herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.

DOCUMENTS

U.S. Patent Documents

| <u>U.S. Patent No.</u> | <u>Issue Date</u> | <u>Inventor</u> |
|------------------------|-------------------|---------------------|
| 5,143,865 | 09/1992 | Hideshima et al. |
| 5,908,317 | 06/1999 | Heo |
| 6,054,772 | 04/2000 | Mostafazadeh et al. |
| 6,097,098 | 08/2000 | Ball |
| 6,150,717 | 11/2000 | Wood et al. |
| 6,208,018 B1 | 03/2001 | Ma et al. |

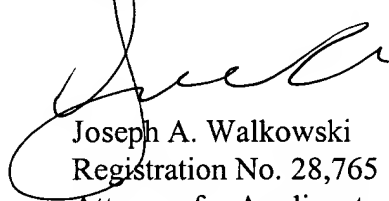
Foreign Patent Documents

| <u>Document No.</u> | <u>Date</u> | <u>Country</u> |
|---------------------|-------------|----------------|
| 11-135663 | 05/1999 | Japan |
| 2000-133669 A | 05/2000 | Japan |

Applicants offer to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

This Supplemental Information Disclosure Statement is filed before the mailing date of a first Office Action on the merits.

Respectfully submitted,



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Date: October 26, 2001

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Enclosures: Form PTO-1449
Copy of documents cited

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